

L Number	Hits	Search Text	DB	Time stamp
1	32	lap\$4 and etch\$4 and mirror\$4 and alkali\$4 and acid\$3 and bond\$5 near5 wafer\$	USPAT	2003/07/23 15:06
2	0	etch\$4 and pit\$4 near4 (deep\$4 or depth\$) and (silicon or wafer) and power adj density and waviness	USPAT	2003/07/23 16:50
5	609	etch\$4 and pit\$4 near4 (deep\$4 or depth\$) and (silicon or wafer)	USPAT	2003/07/23 16:51
3	9	etch\$4 and pit\$4 near4 (deep\$4 or depth\$) and (silicon or wafer) and waviness	USPAT	2003/07/23 16:51
4	19	etch\$4 and pit\$4 near4 (deep\$4 or depth\$) and (silicon or wafer) and power adj density	USPAT	2003/07/23 17:13
6	1	"6461939"	USPAT	2003/07/23 17:13